

# Bill of Materials

**TI DESIGNS**
*TIDA-00193 - RS-485 Interface with Integrated 1.8V Level-Shift Capability*

Item	Quantity	Reference	Part	Footprint	Manufacturer	Manufacturer Part Number	Notes
1	4	BON1,BON2,BON3,BON4	Bump On	Bumpon_Dome_Clear_0p312x0p085in	3M	SJ5302	
2	5	C1,C2,C3,C4,C5	1uF	603		C1608X7R1C105K	
3	3	C6,C7,C8	0.1uF	603		GRM188R71H104KA93D	
4	3	JMP1	Header 2x3	HDR_THVT_2x3_100		HTSW-150-07-G-D	
5	6	JMP2,JMP3,JMP4	Header 1x2	HDR_THVT_1X2_100		HTSW-150-07-G-S	
6	6	R1,R2,R3,R4,R5,R7	10k	805		ERJ-6ENF1002V	
7	1	R6	100	1206		CR1206-8W-1000FT	
8	1	TB1	Terminal Block 1x5	TB_THRTSCR_1x5_100	TE Connectivity	282834-5	
9	1	TB2	Terminal Block 1x8	TB_THRTSCR_1x8_100	TE Connectivity	282834-8	
10	1	TB3	Terminal Block 1x2	TB_THRTSCR_1x2_100	TE Connectivity	282834-2	
11	4	TP1,TP2,TP3,TP4	BLACK	HDR_THVT_1X1_100		5001	
12	2	TP5,TP6	RED	HDR_THVT_1X1_100		5000	
13	3	TP7,TP8,TP10	BLUE	HDR_THVT_1X1_100		5117	
14	4	TP9,TP11,TP12,TP13	GREEN	HDR_THVT_1X1_100		TP-105-40-05	
15	1	U1	SN65HVD01	VQFN_14RGY	TI	SN65HVD01	
16	1	U2	TLV7103318	WSO6DSE	TI	TLV7103318DSE	

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